

ABLEFILM® ECF561E

March 2009

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PRODUCT DESCRIPTION

ABLEFILM[®] ECF561E provides the following product characteristics:

Technology	Rubberized Epoxy
Appearance	Grey
Cure	Heat cure
Product Benefits	Electrically conductive in x, y, z axes Conductive over a high range of frequencies, up the the gigahertz range Flexible for Bonding Mismatched Adherends
Application	Die attach
Carrier Type	Glass fabric
Carrier Thickness	1mil
Filler Type	Silver
Typical Package Application	Substrate attach

ABLEFILM[®] ECF561E electrically conductive die attach adhesive is designed for bonding materials with severely mismatched coefficients of thermal expansion. When used for substrate attach, this adhesive film acts as an electrical ground plane.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Shelf Life @ -40°C (from date of manufacture), year 1

TYPICAL CURING PERFORMANCE

Cure Schedule

1 hour @ 150°C

Alternative Cure Schedule

2 hours @ 125°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Coefficient of Thermal Expansion, ppm/°C:		
Below Tg	100	
Above Tg	380	
Glass Transition Temperature (Tg) by DMTA, °C	47	

Electrical Properties:			
Weight Loss @ 300°C, %	0.55		
Thermal Conductivity @ 121°C, W/mK	1.6		

TYPICAL PERFORMANCE OF CURED MATERIAL

Bond Joint Resistance, ohms/0.5sq inch

Lap Shear Strength, psi:		
Substrate		
	Al to Al	2000
1	Au to Au	2100
	tu to Au	

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

- 1. Allow container to reach room temperature before use.
- DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

- Place precut adhesive film between clean surfaces to be bonded.
- Apply spring loaded clamp or dead weight to provide continuous pressure of at least 2 to 10 psi during cure cycle.
- 3. Place assembly in a preheated oven and cure at the recommended cure schedule.
- ABLEFILM[®] ECF561E adhesive films can be die cut to customer specifications. Tolerances are as close as ±0.005inch in length or width and ±0.001inch in thickness.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.



Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

 $(^{\circ}C \times 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 0.1